LCM Specification

PRODUCT TYPE:	TFT MODULE
PRODUCT P/N:	LH280QV010-40
VERSION:	V00

Cust	omer(客户)
INSPECTION RESULT 检测结果	TESTED BY 检测人	APPROVED BY 确认人

	Supplier(屏厂	
DESIGNED BY	CHECKED BY	APPROVED BY

Revision History

Date	Rev.	Reason
2017.04.15	V00	NEW ISSUE

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■ GENERAL DESCRIPTION

LH280QV010-40 is a TFT dot matrix LCD module. It is composed of a color-LCD panel, driver IC, FPC and a backlight unit. The module display area contains 240x320 pixels. This product accords with RoHS environmental criterion.

■ GENERAL FEATURES

Item	Contents	Unit
LCD Type	TFT TRANSMISSIVE	/
Viewing direction	12:00	O' Clock
Outside Dimensions	50.00(W)*69.20(H)*2.25(T)	mm
Active area (WxH)	43.20(W)*57.60(H)	mm
Number of Dots	240x320	/
Driver IC	ST7789V	/
Colors	65K/262K	/
Backlight Type	4LEDS / White	/
Interface Type	Mcu 8/9/16/18bit, SPI,RGB	/
Input voltage	2.8V/3.0V/3.3V	V

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Power for Circuit Driving	VCC	-0.3	4.6	٧
Power for Circuit Logic	IOVCC	-0.3	4.6	V
Input voltage	Vin	-0.3	VCC + 0.3	٧
Operating temperature	Тор	-20	70	${\mathbb C}$
Storage temperature	Tst	-30	80	${\mathfrak C}$
Humidity	RH	/	90%(Max60°C)	RH

■ ELECTRICAL SPECIFICATIONS

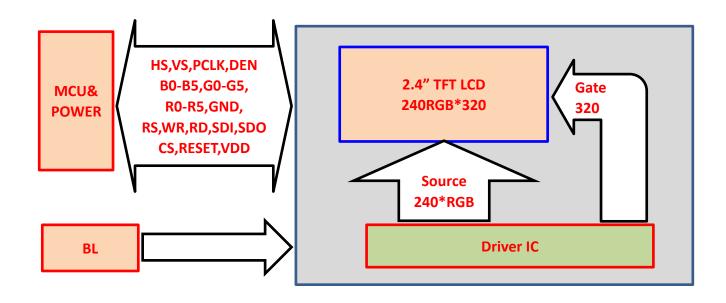
Parameter	Symbol	Min	Тур	Max	Unit
Power for analog/logic	Vcc -GND	2.6	2.8	3.3	V
I/O power supply	IOVCC	1	1	-	V
Input Current	ldd	TBD	TBD	TBD	V
Input voltage ' H ' level	Vih	0.7IOVCC		IOVCC	$^{\circ}$
Input voltage ' L ' level	Vil	GND	0	0.3IOVCC	
Output voltage ' H ' level	Voh	0.8IOVCC		IOVCC	$^{\circ}$ C
Output voltage ' L ' level	Vol	GND	0	0.2IOVCC	RH

■ BACKLIGHT CHARACTERISTICS

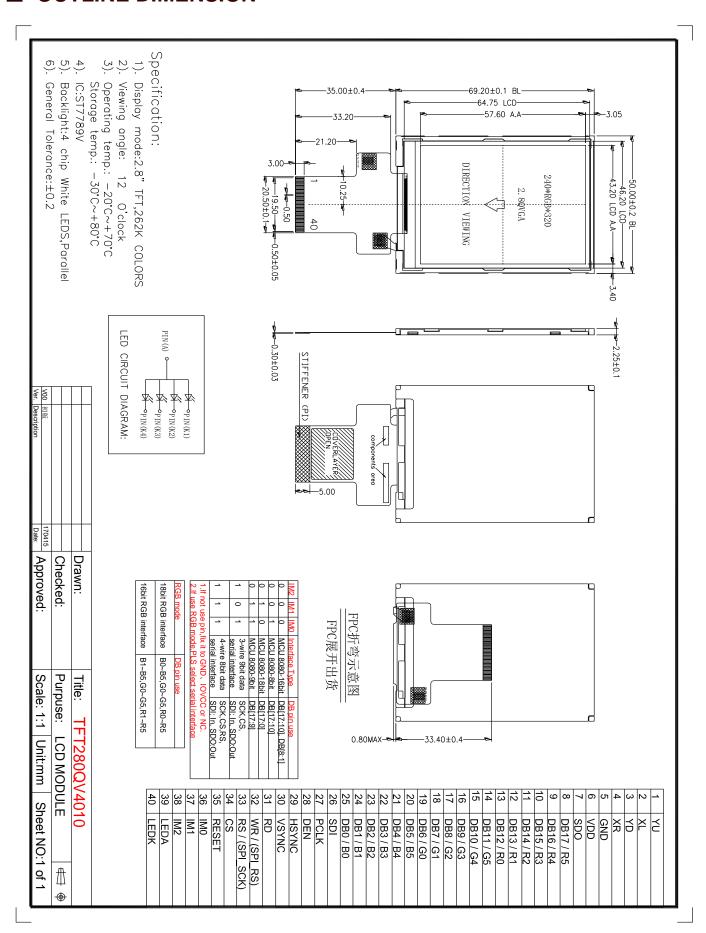
Using condition: constant current driving method If= 80mA(+/-10%)

Item	Symbol	Min	Тур	Max	Unit	Condition
Forward voltage	Vf	3.0	3.2	3.4	V	If=80mA
Luminance with LCD	Lv	1	220	1	cd/m2	If=80mA
Number of LED			4		Pcs	
Connection mode	S		Paralle			

■ BLOCK DIAGRAM



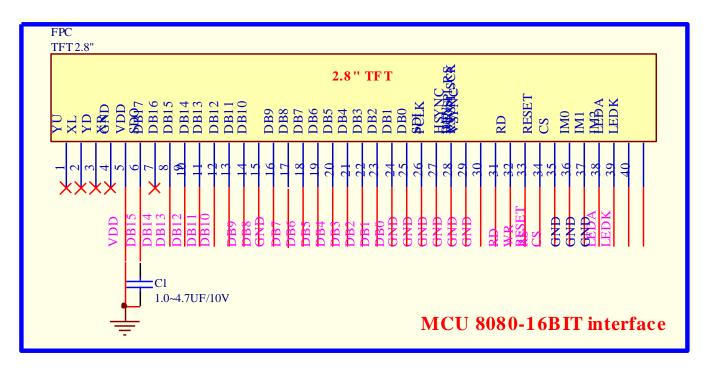
OUTLINE DIMENSION

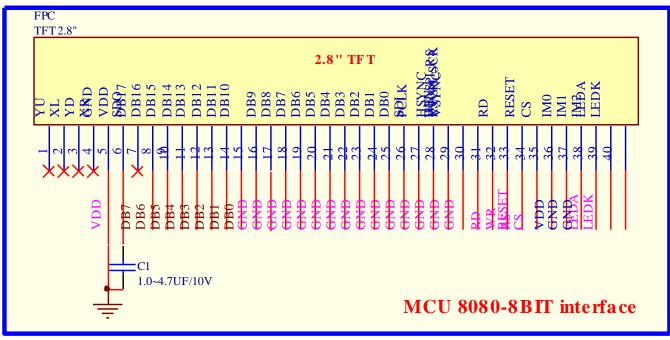


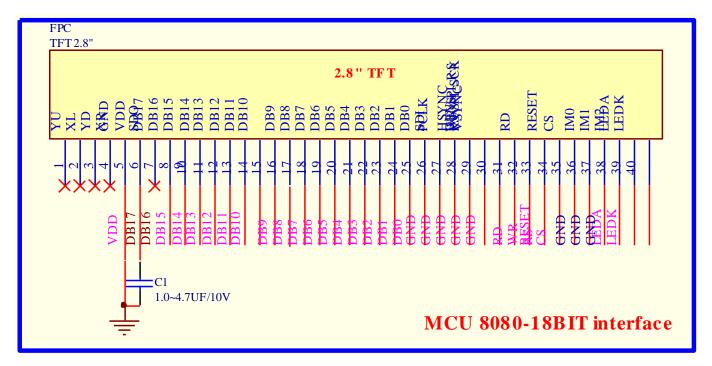
■ PIN DESCRIPTION

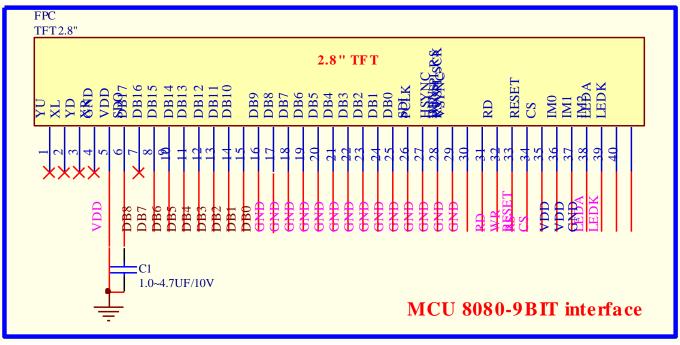
Symbol	DESCRIPTION
<u> </u>	
	TP Up, if not use, Please open it
	TP Left, if not use, Please open it
	TP Down, if not use, Please open it
	TP Right, if not use, Please open it
	Ground
	Power Supply Voltage(2.8V/3.0V/3.3V),
	serial interface output pin
DB11	
DB10	
DB9	Databus
DB8	Databus
DB7	
DB6	
DB5	
DB4	
DB3	
DB2	
DB1	
DB0	
SDI	serial interface input pin
PCLK	Dot clock signal for RGB interface operation
DEN	Data enable signal for RGB interface
HSYNC	Horizontal synchronizing input signal for RGB interface
VSYNC	Vertical synchronizing input signal for RGB interface
RD	Read enable in 8080 MCU parallel interface
WR/SPI_RS	Write enable in MCU parallel interface.
	Display data/command selection pin in 4-line serial interface.
RS/ SPI_SCK	Display data/command selection pin in parallel interface.
	This pin is used to be serial interface clock.
CS	Chip select input pin. Enabled when CS is "L".
RESET	A reset pin
IMO	The MCU interface mode select pin
IM1	The MCU interface mode select pin
IM2	The MCU interface mode select pin
LEDA	LED Anode
LEDK	LED Cathode
	DB9 DB8 DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 SDI PCLK DEN HSYNC VSYNC RD WR/SPI_RS RS/ SPI_SCK CS RESET IM0 IM1 IM2 LEDA

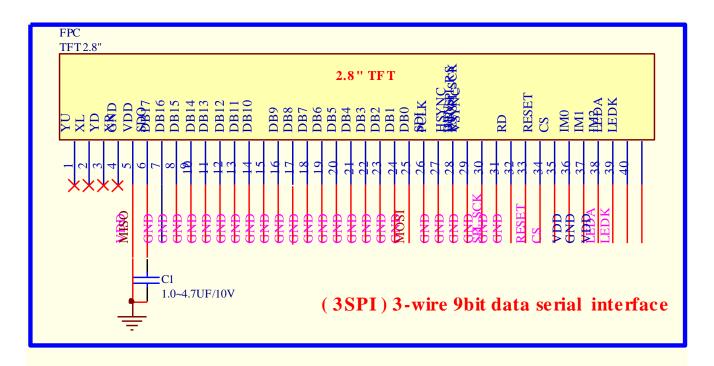
APPLICATION CIRCUIT:

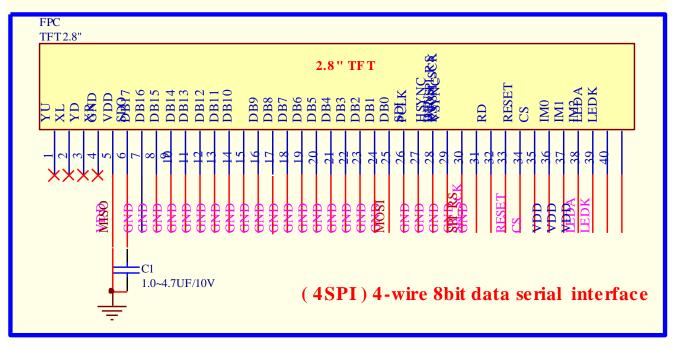


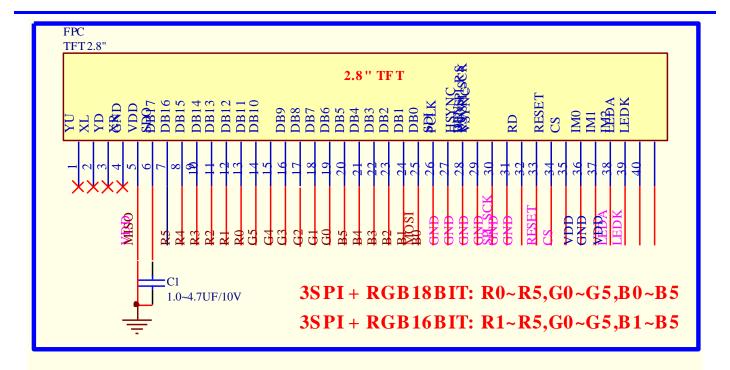


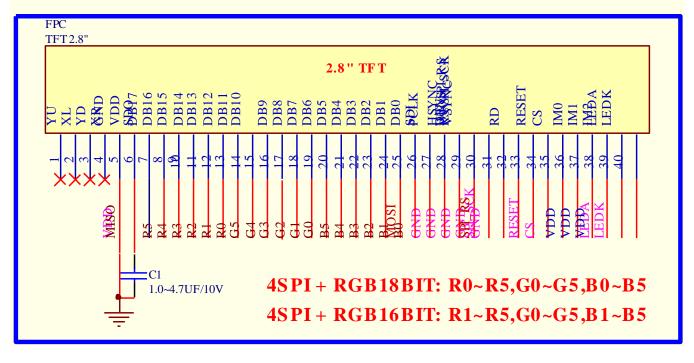












Initial Code:

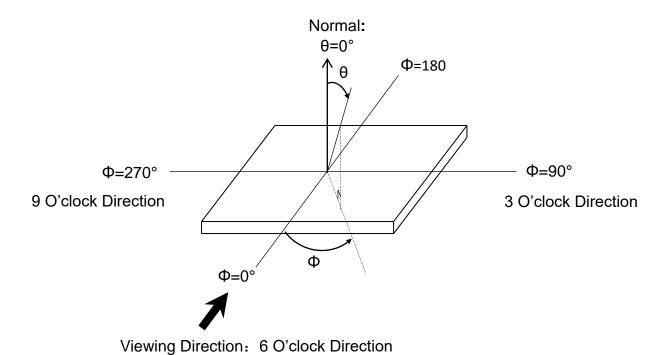
```
//Initial Start 初始化开始
write cmd(0x11);
delayms(150);
write cmd(0xb2);
write_dat(0x0c);
write_dat(0x0c);
write_dat(0x00);
write_dat(0x33);
write_dat(0x33);
write_cmd(0xb7);
write dat(0x35);
write_cmd(0xbb);
write_dat(0x19);
write_cmd(0xc0);
write_dat(0x2c);
write_cmd(0xc2);
write_dat(0x01);
write cmd(0xc3);
write_dat(0x12);
write_cmd(0xc4);
write_dat(0x20);
write_cmd(0xc6);
write_dat(0x0f);
write_cmd(0xd0);
write_dat(0xa4);
write_dat(0xa1);
//---- gamma setting-----
write_cmd(0xe0);
write_dat(0xd0);
write_dat(0x04);
write_dat(0x0d);
write_dat(0x11);
write_dat(0x13);
write_dat(0x2b);
write_dat(0x3f);
write_dat(0x54);
write_dat(0x4c);
write dat(0x18);
write dat(0x0d);
write_dat(0x0b);
write_dat(0x1f);
write_dat(0x23);
```

```
write_cmd(0xe1);
write_dat(0xd0);
write_dat(0x04);
write dat(0x0c);
write_dat(0x11);
write_dat(0x13);
write_dat(0x2c);
write_dat(0x3f);
write_dat(0x44);
write_dat(0x51);
write_dat(0x2f);
write_dat(0x1f);
write_dat(0x1f);
write_dat(0x20);
write_dat(0x23);
#ifdef RGB_interface
write_cmd(0xB0);
write_dat(0x11);
write_dat(0xF0);
write_cmd(0xB1);
write_dat(0x40);
write_dat(0x09);
write_dat(0x14);
#endif
#if defined(RGB interface)||defined(RGB666)
write_cmd(0x3a);
write dat(0x66);
#else
write_cmd(0x3a);
write_dat(0x65);
#endif
write_cmd(0x36);
write dat(0x00);
write_cmd(0x29);
//Initial Code END 初始化结束
//说明:
//RGB_interface: SPI+RGB接口
//RGB666: 指MCU接口显示RGB666格式图片
//默认普通MCU与SPI接口显示RGB565格式图片
```

■ OPTICAL SPECIFICATIONS

Item		Symbol	Condition	Min	Тур	Max	Unit	Note
Response ti	me	Tr+Tf	0-0°	-	30	40	ms	/
Contrast ra	tio	Cr	θ=0° Φ=0°	300	500	-	-	/
Luminance unif	ormity	δ WHITE	Ta=25℃	80	-	-	%	/
			Ф =90°	1	60	1	deg	
Viewing angle	rongo	θ	Ф =270°	-	60	-	deg	,
Viewing angle	range	Ð	Ф=0°	-	60	-	deg	/
			Ф =180°	-	45	-	deg	
	Dod	Х		0.590	0.610	0.630		
	Red	у		0.309	0.329	0.349		
	0	Х		0.279	0.299	0.319		
CIE(x,y)	Green	у	θ=0°	0.547	0.567	0.687	,	,
chromaticity	Dluc	Х	Ф=0° Та=25°С	0.123	0.143	0.163	'	/
	Blue	у	.u. _u	0.091	0.111	0.131		
	\\/bitc	Х		0.288	0.308	0.328		
	White	у		0.307	0.327	0.347		

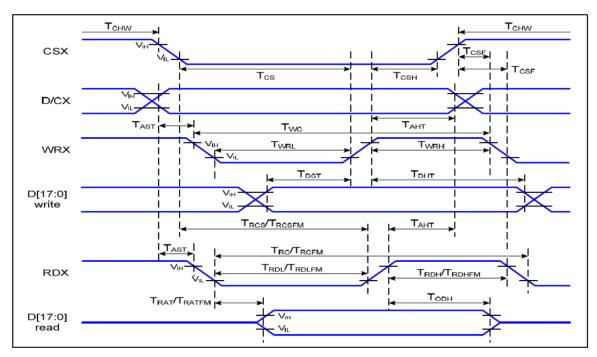
Definition of Viewing Angle θ and Φ



■ TIMING CHARACTERISTICS

Please refer to the datasheet of ST7789S for details.

8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

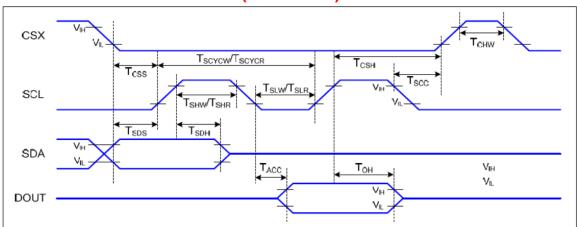


Note: Ta = -30 to 70 $^{\circ}$ C, IOVCC=1.65V to 3.3V, VCC=2.5V to 3.3V, GND=0V

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	
DICX	T _{AHT}	Address hold time (Write/Read)	10		ns	-
	T _{CHW}	Chip select "H" pulse width	0		ns	
	T _{CS}	Chip select setup time (Write)	15		ns	
CSX	T _{RCS}	Chip select setup time (Read ID)	45		ns	
CSX	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
	T _{wc}	Write cycle	66		ns	
WRX	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T _{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX	T _{RCFM}	Read cycle (FM)	450		ns	When read from
	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	
(FM)	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	frame memory
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF

T _{DHT}	Data hold time	10		ns
T _{RAT}	Read access time (ID)		40	ns
T _{RATFM}	Read access time (FM)		340	ns
T _{ODH}	Output disable time	20	80	ns

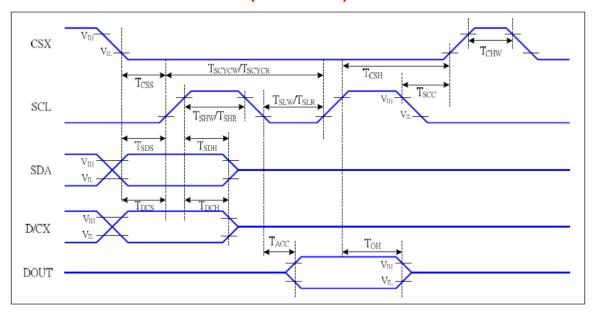
Serial Interface Characteristics (3-line serial):



Note: Ta = -30 to 70 $^{\circ}$ C, IOVCC=1.65V to 3.3V, VCC=2.5V to 3.3V, GND=0V

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
DOUT	T _{OH}	Output disable time	15	50	ns	For minimum CL=8pF

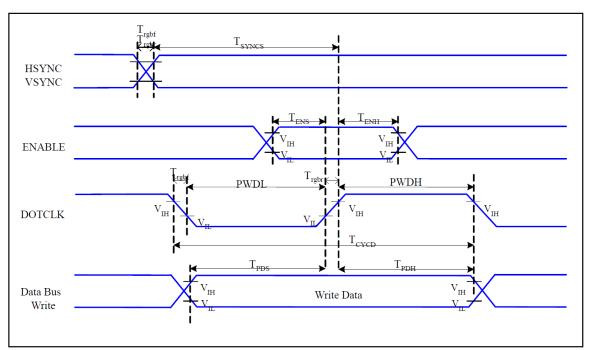
Serial Interface Characteristics (4-line serial):



Note: Ta = -30 to 70 $\,^{\circ}\,$ C, IOVCC=1.65V to 3.3V, VCC=2.5V to 3.3V, GND=0V

Signal	Symbol	Parameter	MIN	MAX	Unit	Description	
	T _{CSS}	Chip select setup time (write)	15		ns		
	T _{CSH}	Chip select hold time (write)	15		ns		
CSX	T _{CSS}	Chip select setup time (read)	60		ns		
	T _{scc}	Chip select hold time (read)	65		ns		
	T _{CHW}	Chip select "H" pulse width	40		ns		
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns		
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	ram	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns		
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	-read command & data	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	ram	
DICY	T _{DCS}	D/CX setup time	10		ns		
D/CX	T _{DCH}	D/CX hold time	10		ns		
SDA	T _{SDS}	Data setup time	10		ns		
(DIN)	T _{SDH}	Data hold time	10		ns		
DOLLT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF	
DOUT	Тон	Output disable time	15	50	ns	For minimum CL=8pF	

RGB Interface Characteristics:

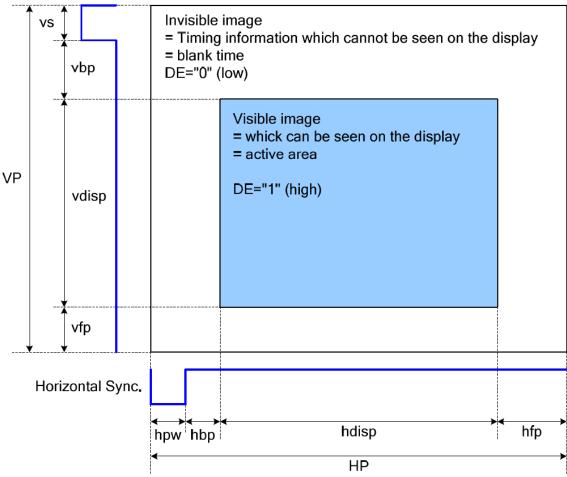


Note: Ta = -30 to 70 $^{\circ}$ C, IOVCC=1.65V to 3.3V, VCC=2.5V to 3.3V, GND=0V

Signal	Symbol	Parameter		MAX	Unit	Description
HSYNC,	Ŧ	VOVALO LIOVALO O del un Timo e	20			
VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T _{ENS}	Enable Setup Time	25	-	ns	
ENABLE	T _{ENH}	Enable Hold Time	25	-	ns	
	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
DOTCLK	T _{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T _{PDS}	PD Data Setup Time	50	-	ns	
DB	T_{PDH}	PD Data Hold Time	50	-	ns	

DRAM Access Area by RGB Interface





Please refer to the following table for the setting limitation of RGB interface signals.

Parameter	Symbol	Min.	Тур.	Max.	Unit
Horizontal Sync. Width	hpw	2	10	hpw.lhhn=21	Clock
Horizontal Sync. Back Porch	hbp	4	10	hpw+hbp=31	Clock
Horizontal Sync. Front Porch	hfp	2	38	-	Clock
Vertical Sync. Width	VS	1	4		Line
Vertical Sync. Back Porch	vbp	1	4	vs+vbp=127	Line
Vertical Sync. Front Porch	vfp	1	8	-	Line

Note:

- 1. Typical value are related to the setting of dot clock is 7MHz and frame rate is 70Hz..
- 2.If the setting of hpw is 10 dot clocks and hbp is 10 dot clocks, the setting of HBP in command B1h is 20 dot clocks
- 3.In with ram mode, hpw+hbp+hfp≥22 (default)
- 4.In without ram mode, hpw+hbp≥20

■ INSPECTION CRITERION

Sampling Method

Unless otherwise agreed upon in writing, the sampling inspection shall be applied to the Customer's incoming inspection.

1 Lot size: Quantity per shipment lot

2 Sampling type: Normal inspection, single sampling

3 Inspection level: II

4 Sampling table: MIL-STD-105D

5 Acceptable Quality Level(AQL): Major=0.65 Minor=1.5

Inspection Method

1) Ambient Condition:

a. Temperature: Room temperature $25\pm5^{\circ}$ C

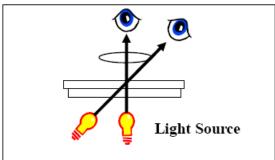
b. Illumination: Single fluorescent lamp non-directive (300 to 700 Lux)

2) Viewing distance

The distance between the LCD and the inspector's eyes shall be at least 30-50cm.

3) Viewing Angle

The inspection shall be conducted within normal viewing angle range.



Major Defect

No	Items	Inspection Standard	Classification of defects
1	All functional defects	nctional 3.Missing vertical, horizontal segment 4 Short circuit	
2	Missing	Missing component	Major
3	Outline dimension	9	
4	linearity	No more than 1.5%	

Cosmetic Defect

No	Items	Inspe	Classification of defects	
	Clear Spot, Black Spot, white Spot,	For dark/white spot, size Φ is defined as Φ=(x+y)/2	y x	
	defect Pinhole,	Size(mm) Acceptable Qty		Minor
1	Foreign	Φ≤0.15 Ignore		Minor
	Particle, polarizer	0.15<Φ≤0.20	2	
	Dirt TP Dirt	0.20<Φ≤0.30	1	
	I P Dirt	Ф>0.30	0	
	(line defect) Black and White line Polarizer scratch	Define: Widtl	h W ↓ Length L	
		Width(mm)	Length(mm);Acceptable Qty	
2		W≤0.03	Ignore	Minor
		0.03 <w≤0.05< td=""><td>L≤3.0; N≤2</td><td></td></w≤0.05<>	L≤3.0; N≤2	
		0.05 <w≤0.1 l≤2.0;="" n≤2<="" td=""><td>]</td></w≤0.1>]
		0.1 <w< td=""><td>Define as spot defect</td><td></td></w<>	Define as spot defect	
	/			
	Dim Spots Circle	Size(mm)	Acceptable Qty	
3		Circle shaped and dim edged $\Phi \le 0.2$ Ignore 2		Minor
	dim edged			IVIIIIOI
	defects	0.40<Φ≤0.60	1	
		Ф>0.60	0	

No	Items	Inspection Standard				Classification of defects
		(1) Chins on corner	of defects			
(1) Chips on corner (A:LCD Glass of X(mm ≤2.0) Notes: S=contact pad length Chips on the corner of terminal shall rextend into the ITO pad or expose pe (2) Chips on corner (TP Glass defect TP defect Glass defect TP defect				Y(mm) ≤S of be allowed the second of the	Minor	
		X(mm) ≤3.0 <inner t<="" td=""><td>Y(mm) porder line of the sea</td><td></td><td>(mm) sregard</td><td></td></inner>	Y(mm) porder line of the sea		(mm) sregard	
	(4) Usual surface cracks (TP Glass defect) X(mm) Y(mm) Z(mm) ≤6.0 <2.0 Disregard (5) Crack (Cracks tend to break are not allowed.)					

RELIABILITY

N0.	TEST ITEM	CONDITIONS
1	High Temperature Storage	80°C; 96 hrs
2	Low Temperature Storage	-30℃;96 hrs
3	HighTemperature Operation	70°C; 96 hrs
4	Low Temperature Operation	-20℃;96 hrs
5	High Temperature and High Humidity Operation	50℃, 90% RH; 96 hrs
6	Thermal shock(Storage)	-20°C (0.5Hr)→70°C (0.5Hr) 100 Cycles

NOTE:

- 1. All judgement of display are performed after temperature of panel return to room temperature.
- 2. Display function should be no change under normal operating condition.
- 3. Under no condensation of dew.
- 4. WE only guarantee the above 6 test items, and without guarantee the others.

PRECAUTIONS

Handing Precautions

- (1) The display panel is made of glass and polarizer. As glass is fragile, it tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- (2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- (3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).
- (4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.
- (5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents
- Isopropyl alcohol
- Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

- (6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
- Water

- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

- (7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- (8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- (9) Do not attempt to disassemble or process the LCD module.
- (10) NC terminal should be open. Do not connect anything.
- (11) If the logic circuit power is off, do not apply the input signals.
- (12) Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.
- Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist LCM.

Storage Precautions

When storing the LCD modules, the following precaution is necessary.

- (1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.
- (2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0° C and 35° C.
- (3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped).

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability. To minimize the performance degradation of the LCD modules resulting from destruction

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
- -Terminal electrode sections.